



PXN8R3-30QL

30 V, N-channel Trench MOSFET

2 November 2020

Product data sheet

1. General description

N-channel enhancement mode Field-Effect Transistor (FET) in an MLPAK33 (SOT8002) Surface-Mounted Device (SMD) plastic package using Trench MOSFET technology.

2. Features and benefits

- Logic-level compatible
- Trench MOSFET technology
- Ultra low Q_G and Q_{GD} for high system efficiency, especially at higher switching frequencies
- Superfast switching with soft-recovery
- Low spiking and ringing for low EMI designs
- MLPAK33 package (3.3 x 3.3 mm footprint)

3. Applications

- DC to DC conversion
- Battery management
- Low-side load switch
- Switching circuits

4. Quick reference data

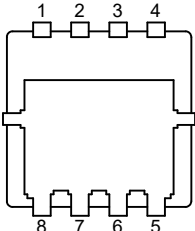
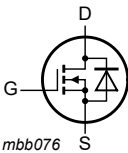
Table 1. Quick reference data

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
V _{DS}	drain-source voltage	T _j = 25 °C		-	-	30	V
V _{GS}	gate-source voltage			-20	-	20	V
I _D	drain current	V _{GS} = 10 V; T _{amb} = 25 °C; t ≤ 5 s	[1]	-	-	18.3	A
Static characteristics							
R _{DSon}	drain-source on-state resistance	V _{GS} = 10 V; I _D = 11.4 A; T _j = 25 °C		-	7.1	8.3	mΩ
		V _{GS} = 4.5 V; I _D = 9.8 A; T _j = 25 °C		-	8.9	11.1	mΩ
Dynamic characteristics							
Q _{G(tot)}	total gate charge	V _{DS} = 15 V; I _D = 9.8 A; V _{GS} = 4.5 V; T _j = 25 °C		-	5.1	7.7	nC

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and mounting pad for drain 6 cm².

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	S	source	 MLPAK33 (SOT8002-1)	
2	S	source		
3	S	source		
4	G	gate		
5	D	drain		
6	D	drain		
7	D	drain		
8	D	drain		

6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
PXN8R3-30QL	MLPAK33	plastic thermal enhanced surface mounted package; mini leads; 8 terminals; pitch 0.65 mm; 3.3 x 3.3 x 0.8 mm body	SOT8002-1

7. Marking

Table 4. Marking codes

Type number	Marking code
PXN8R3-30QL	9AD

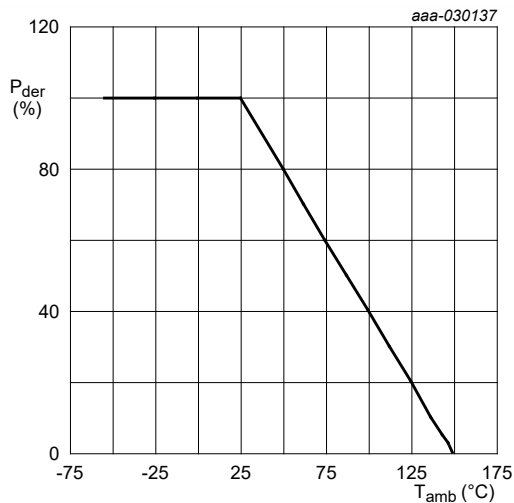
8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

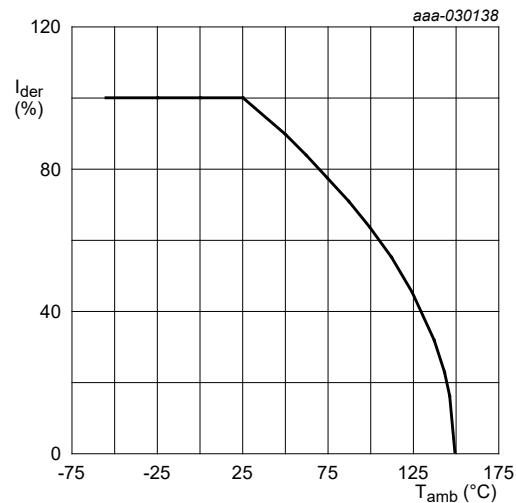
Symbol	Parameter	Conditions		Min	Max	Unit
V _{DS}	drain-source voltage	T _j = 25 °C		-	30	V
V _{GS}	gate-source voltage			-20	20	V
I _D	drain current	V _{GS} = 10 V; T _{amb} = 25 °C; t ≤ 5 s	[1]	-	18.3	A
		V _{GS} = 10 V; T _{amb} = 25 °C	[1]	-	11.4	A
		V _{GS} = 10 V; T _{amb} = 100 °C	[1]	-	7.2	A
		V _{GS} = 10 V; T _{sp} = 25 °C		-	31	A
I _{DM}	peak drain current	T _{amb} = 25 °C; single pulse; t _p ≤ 10 μs		-	293	A
P _{tot}	total power dissipation	T _{amb} = 25 °C; t ≤ 5 s	[1]	-	4.3	W
			[1]	-	1.7	W
		T _{sp} = 25 °C		-	12.5	W
T _j	junction temperature			-55	150	°C
T _{amb}	ambient temperature			-55	150	°C
T _{stg}	storage temperature			-65	150	°C
Source-drain diode						
I _S	source current	T _{amb} = 25 °C	[1]	-	1.5	A
Avalanche ruggedness						
E _{DS(AL)S}	non-repetitive drain-source avalanche energy	T _{j(initial)} = 25 °C; I _D = 1.7 A; DUT in avalanche (unclamped)		-	25	mJ

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and mounting pad for drain 6 cm².



$$P_{der} = \frac{P_{tot}}{P_{tot}(25^{\circ}\text{C})} \times 100\%$$

Fig. 1. Normalized total power dissipation as a function of ambient temperature



$$I_{der} = \frac{I_D}{I_D(25^{\circ}\text{C})} \times 100\%$$

Fig. 2. Normalized continuous drain current as a function of ambient temperature

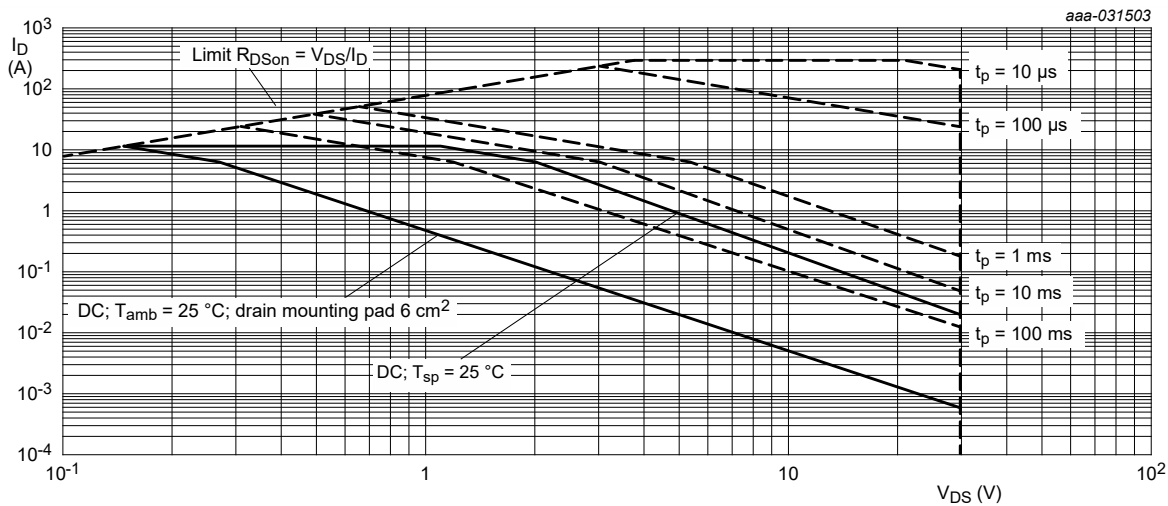


Fig. 3. Safe operating area; junction to ambient; continuous and peak drain currents as a function of drain-source voltage

9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1]	-	150	190	K/W
			[2]	-	60	75	K/W
		in free air; $t \leq 5$ s	[2]	-	24	29	K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point			-	7	10	K/W

- [1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and mounting pad for drain 6 cm².

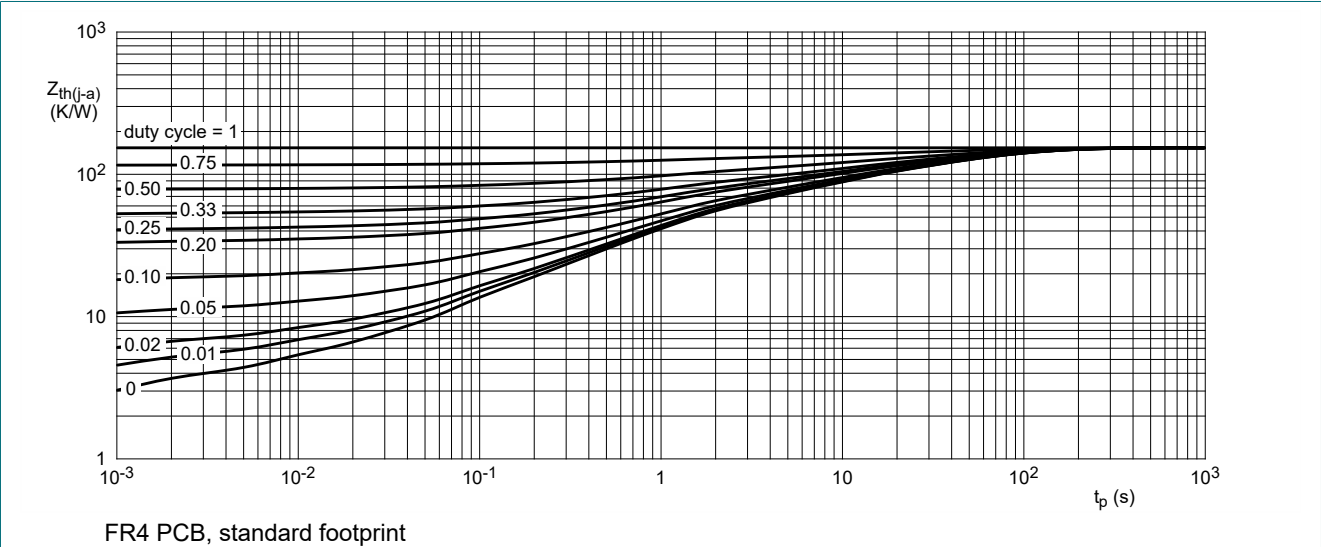


Fig. 4. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

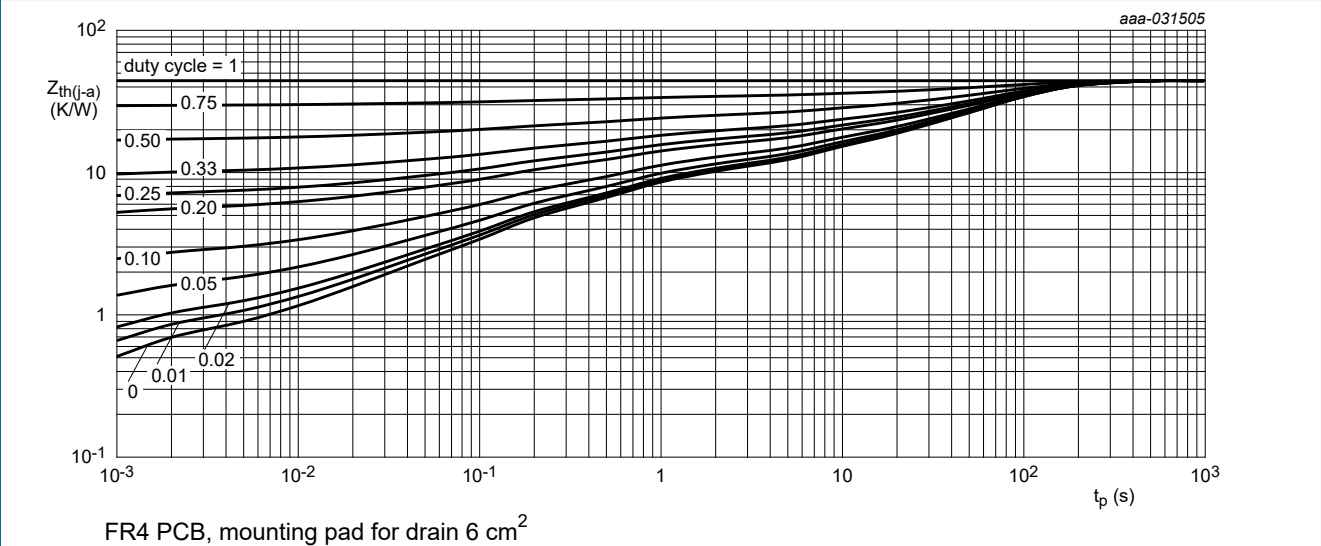


Fig. 5. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Static characteristics							
V _{(BR)DSS}	drain-source breakdown voltage	I _D = 250 μA; V _{GS} = 0 V; T _j = 25 °C		30	-	-	V
V _{GSth}	gate-source threshold voltage	I _D = 250 μA; V _{DS} = V _{GS} ; T _j = 25 °C		1.2	1.7	2.2	V
I _{DSS}	drain leakage current	V _{DS} = 30 V; V _{GS} = 0 V; T _j = 25 °C		-	-	1	μA
I _{GSS}	gate leakage current	V _{GS} = 20 V; V _{DS} = 0 V; T _j = 25 °C		-	-	0.1	μA
		V _{GS} = -20 V; V _{DS} = 0 V; T _j = 25 °C		-	-	-0.1	μA
R _{DSon}	drain-source on-state resistance	V _{GS} = 10 V; I _D = 11.4 A; T _j = 25 °C		-	7.1	8.3	mΩ
		V _{GS} = 10 V; I _D = 11.4 A; T _j = 150 °C		-	11	12.9	mΩ
		V _{GS} = 4.5 V; I _D = 9.8 A; T _j = 25 °C		-	8.9	11.1	mΩ
g _{fs}	forward transconductance	V _{DS} = 10 V; I _D = 11.4 A; T _j = 25 °C		-	25	-	S
R _G	gate resistance	f = 1 MHz		-	2.3	-	Ω
Dynamic characteristics							
Q _{G(tot)}	total gate charge	V _{DS} = 15 V; I _D = 11.4 A; V _{GS} = 10 V; T _j = 25 °C		-	10.6	15.9	nC
		V _{DS} = 15 V; I _D = 9.8 A; V _{GS} = 4.5 V; T _j = 25 °C		-	5.1	7.7	nC
Q _{GS}	gate-source charge			-	1.9	-	nC
Q _{GS(th)}	pre-threshold gate-source charge			-	1.2	-	nC
Q _{GS(th-pl)}	post-threshold gate-source charge			-	0.7	-	nC
Q _{GD}	gate-drain charge			-	1.3	-	nC
V _{GSpl}	gate-source plateau voltage	V _{DS} = 15 V; I _D = 9.8 A; T _j = 25 °C		-	2.6	-	V
C _{iss}	input capacitance	V _{DS} = 15 V; f = 1 MHz; V _{GS} = 0 V; T _j = 25 °C		-	760	-	pF
C _{oss}	output capacitance			-	270	-	pF
C _{rss}	reverse transfer capacitance			-	42	-	pF
t _{d(on)}	turn-on delay time	V _{DS} = 15 V; I _D = 9.8 A; V _{GS} = 4.5 V; R _{G(ext)} = 5 Ω; T _j = 25 °C		-	5	-	ns
t _r	rise time			-	8	-	ns
t _{d(off)}	turn-off delay time			-	6	-	ns
t _f	fall time			-	3	-	ns
Source-drain diode							
V _{SD}	source-drain voltage	I _S = 1.5 A; V _{GS} = 0 V; T _j = 25 °C		-	0.7	1.2	V
t _{rr}	reverse recovery time	I _S = 1.5 A; dI _S /dt = -100 A/μs; V _{GS} = 4.5 V; V _{DS} = 15 V; T _j = 25 °C		-	15	-	ns
Q _r	recovered charge			-	6	-	nC
t _a	reverse recovery rise time			-	8	-	ns
t _b	reverse recovery fall time			-	7	-	ns

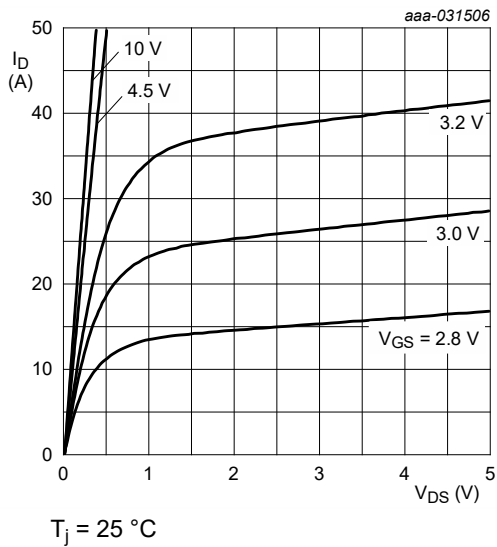


Fig. 6. Output characteristics: drain current as a function of drain-source voltage; typical values

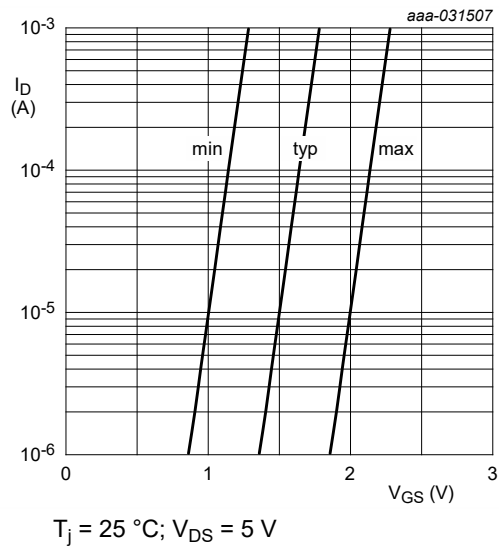


Fig. 7. Subthreshold drain current as a function of gate-source voltage

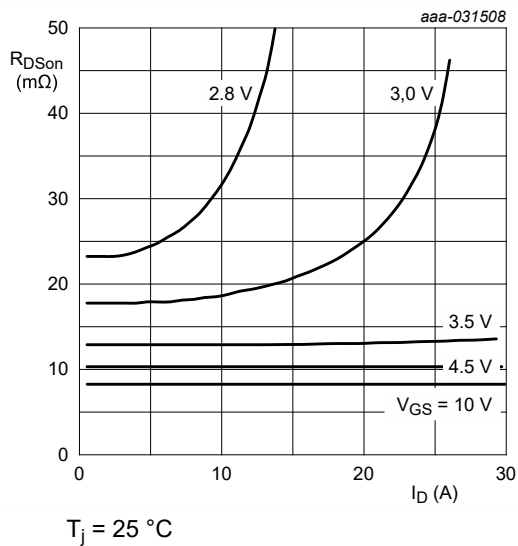


Fig. 8. Drain-source on-state resistance as a function of drain current; typical values

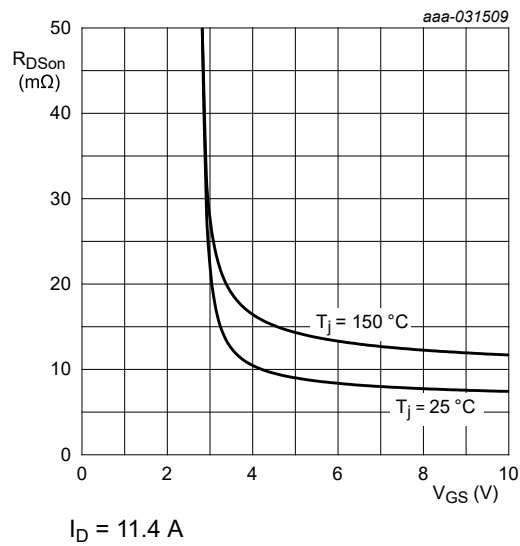


Fig. 9. Drain-source on-state resistance as a function of gate-source voltage; typical values

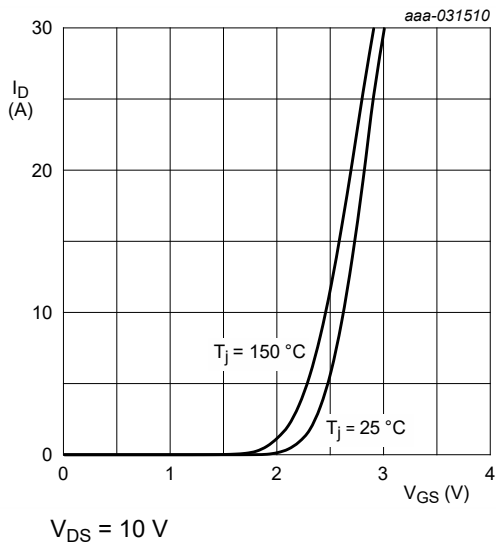


Fig. 10. Transfer characteristics: drain current as a function of gate-source voltage; typical values

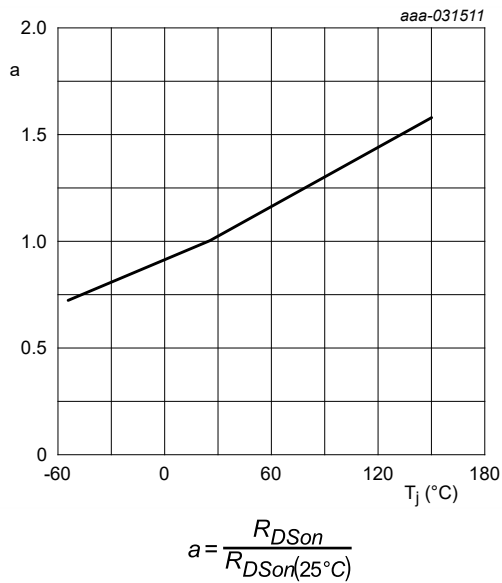


Fig. 11. Normalized drain-source on-state resistance as a function of junction temperature; typical values

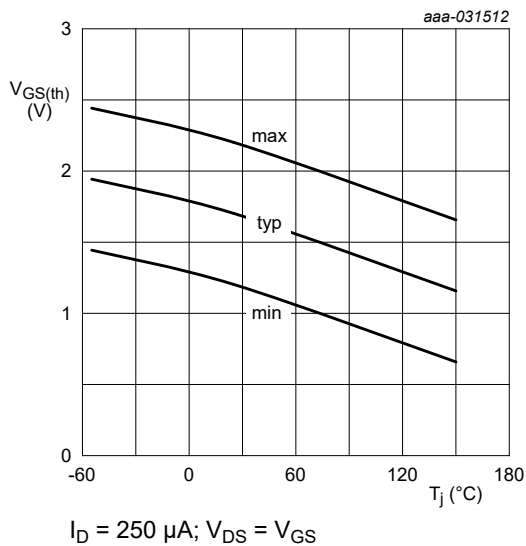


Fig. 12. Gate-source threshold voltage as a function of junction temperature

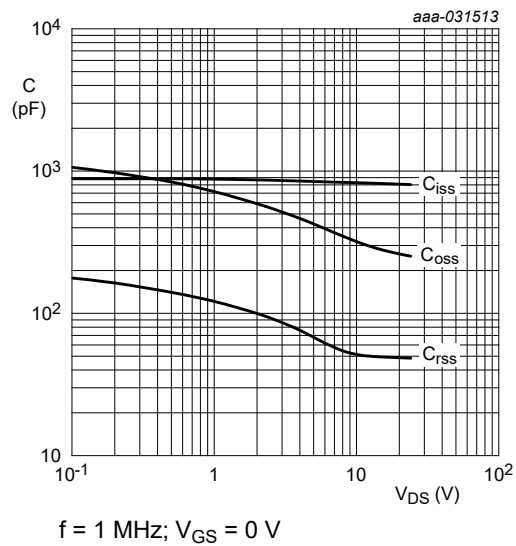


Fig. 13. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values

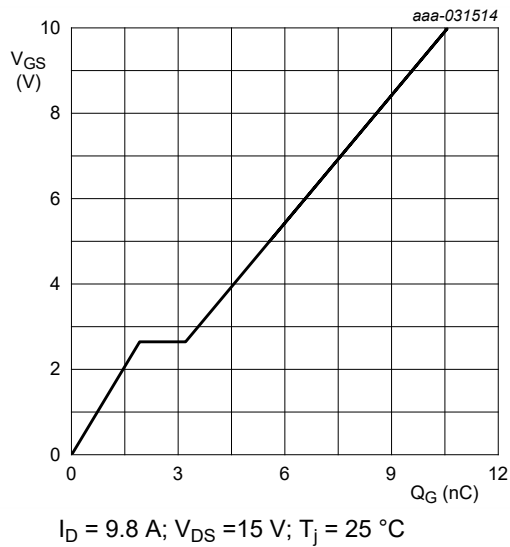


Fig. 14. Gate-source voltage as a function of gate charge; typical values

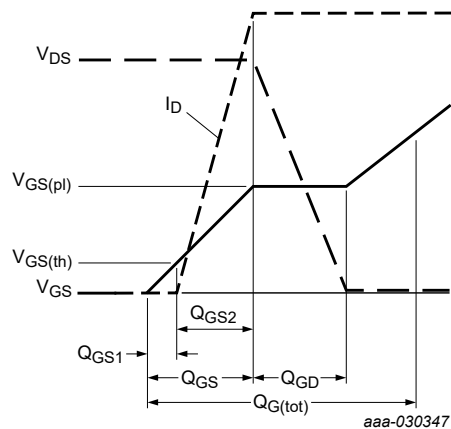


Fig. 15. Gate charge waveform definitions

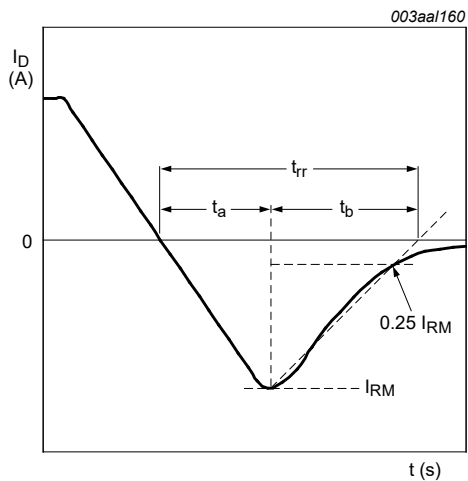


Fig. 16. Reverse recovery timing definition

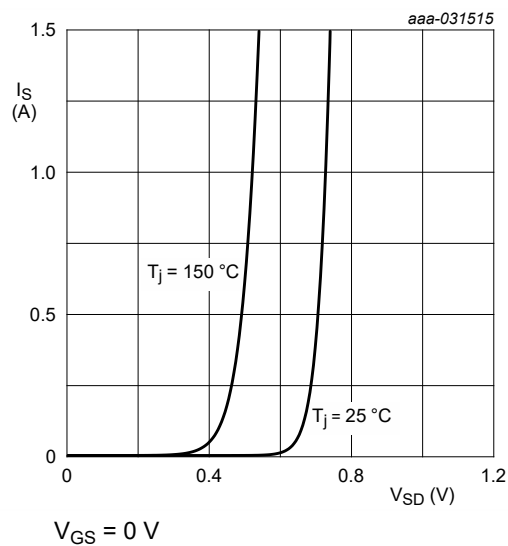


Fig. 17. Source current as a function of source-drain voltage; typical values

11. Test information

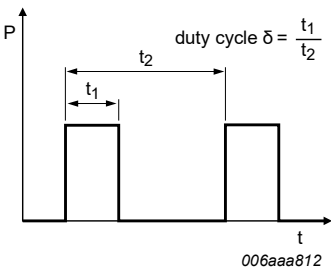
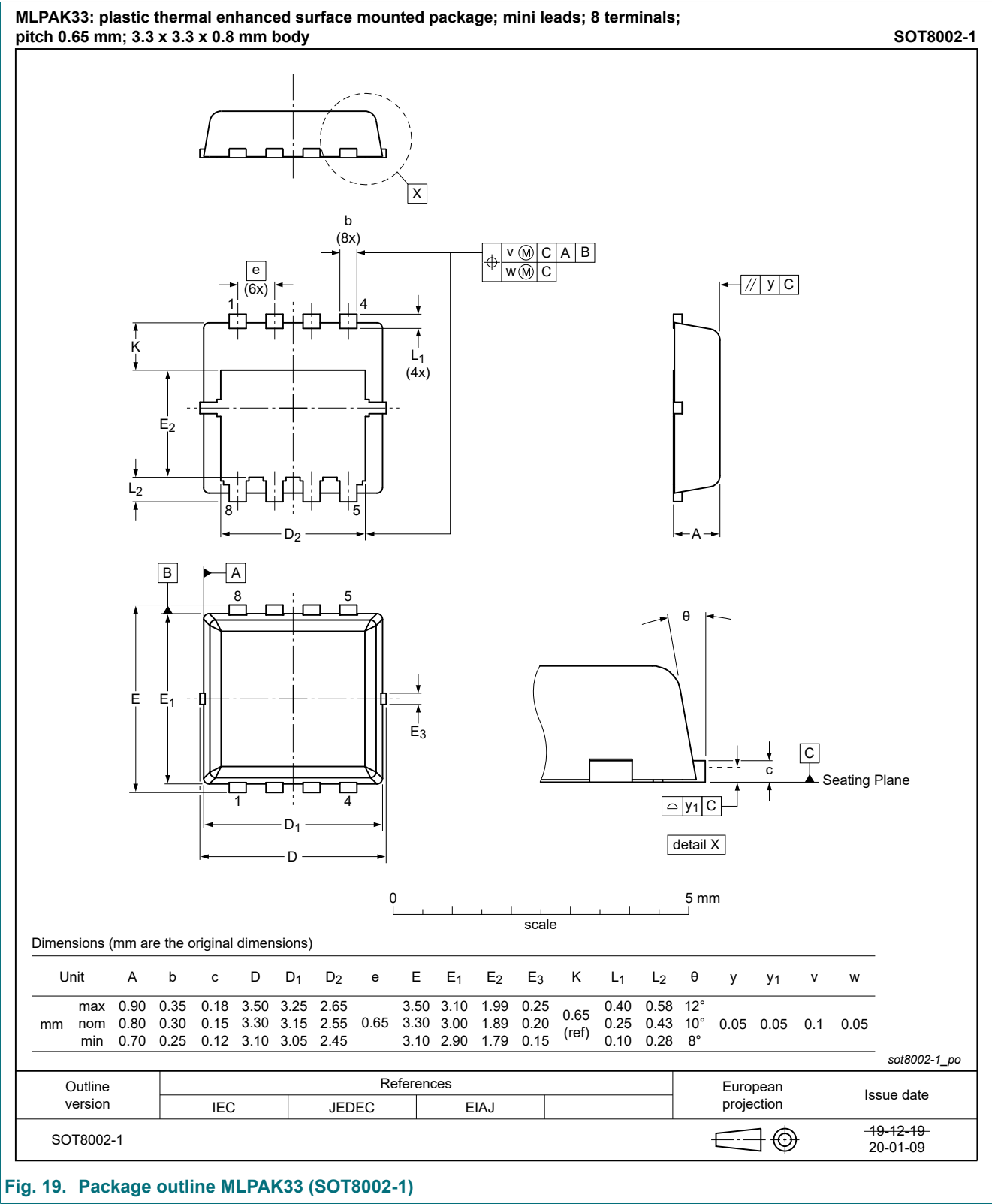


Fig. 18. Duty cycle definition

12. Package outline



13. Soldering

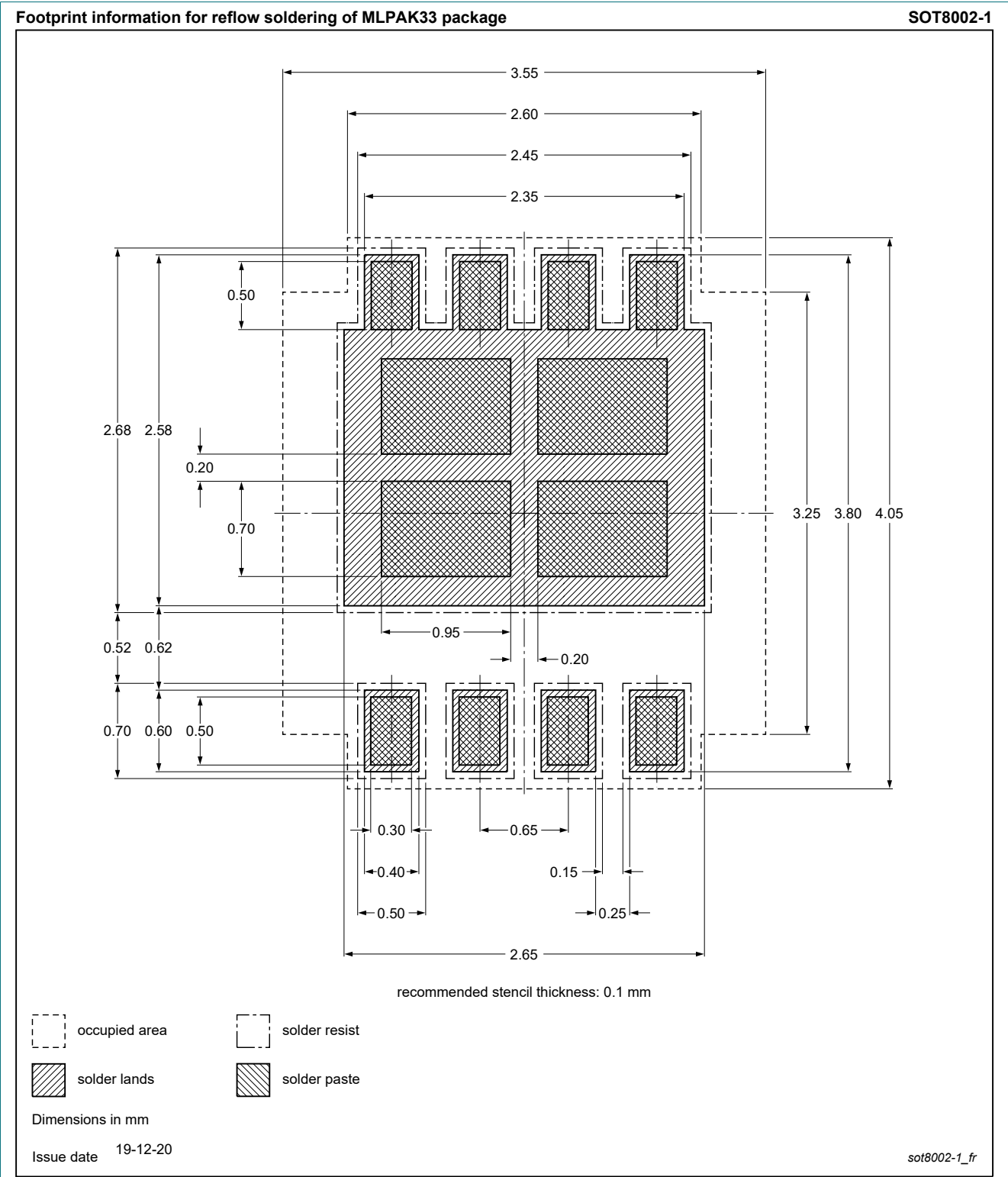


Fig. 20. Reflow soldering footprint for MLPAK33 (SOT8002-1)

14. Revision history

Table 8. Revision history

Data sheet ID	Release date	Data sheet status	Change notice	Supersedes
PXN8R3-30QL v.2	20201102	Product data sheet	-	PXN8R3-30QL v.1
Modifications:	Chapter "Thermal characteristics": Typo corrected.			
PXN8R3-30QL v.1	20200428	Preliminary data sheet	-	-

15. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions".
- [3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the internet at <https://www.nexperia.com>.

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